

View Online at <https://aerobasegroup.com/nsn/5910-01-369-2710>

Body Style:

Chip type

Reliability Indicator:

Established

Reliability Failure Rate Level In Percent:

0.001

Terminal Length:

0.5 millimeters

Body Length:

2.0 millimeters

Body Width:

1.25 millimeters

Body Height:

1.3 millimeters

Schematic Diagram Designator:

No common or grounded electrode (s)

Insulation Resistance At Maximum Operating Temp:

10.0 megohm-microfarads

Capacitance Value Per Section:

3.000 picofarads single section

Nonderated Operating Temp:

Between -55.0 degrees celsius and 125.0 degrees celsius

Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:

0.0 single section

Nonderated Continuous Voltage Rating And Type Per Section:

100.0 dc single section

Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:

-30.0/+30.0 single section

Tolerance Range Per Section:

-0.50/+0.50 picofarads single section

Case Material:

Ceramic

Insulation Resistance At Reference Temp:

1000.0 megohm-microfarads

Dissipation Factor At Reference Tempurature In Percent:

0.150

Terminal Surface Treatment:

Solder

Test Data Document:

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

Terminal Type And Quantity:

2 bonding pad

Specification Data:

81349-mil-c-55681/7 government specification

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

A010b0